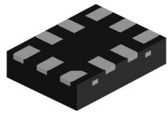


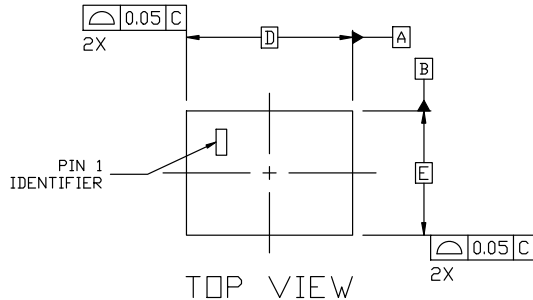
MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

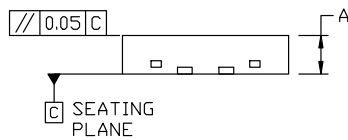


X2QFN10 1.60x1.20x0.37, 0.40P
CASE 722AC
ISSUE A

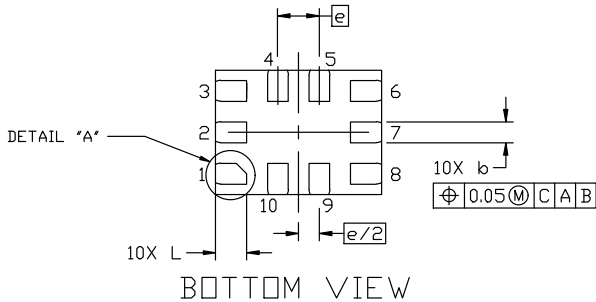
DATE 15 NOV 2023



TOP VIEW



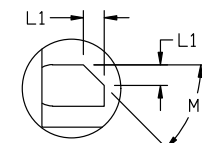
SIDE VIEW



BOTTOM VIEW

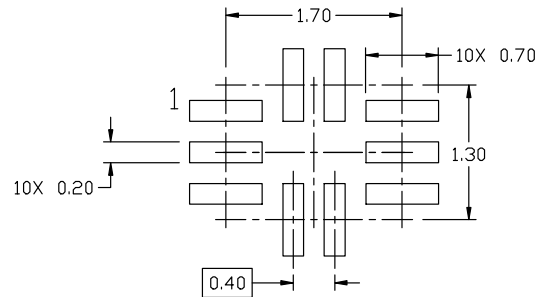
NOTES:

1. DIMENSIONS AND TOLERANCING AS PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS.



DETAIL "A"
 SCALE 2:1

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.34	0.37	0.40
b	0.15	0.20	0.25
D	1.60 BSC		
E	1.20 BSC		
e	0.40 BSC		
L	0.25	0.30	0.35
L1	0.10 (REF)		
M	45° (REF)		



RECOMMENDED
 MOUNTING FOOTPRINT

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCES MANUAL, SOLDERRM/D.

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DESCRIPTION:	X2QFN10 1.60x1.20x0.37, 0.40P	PAGE 1 OF 1

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